AEC/APC Symposium Asia 2023 Program

*program schedule is subject to change.

		Chair		Paper#	Title	Speaker	Affiliation
Hitotsubashi Memorial Hall							
9:15	9:45				Registration Starts / Door Open		
Opening & Tutorial 1 Speech							
9:45	9:50	Hirai Toshiya KOKUSAI ELECTRIC			Opening Remarks from AEC/APC Asia	Hidetaka Nishimura	Renesas Electronics
9:50	9:55				Program Outline	Hidenori Kakinuma	Kioxia Corporation
9:55	10:40			**Tutorial-1**	**<ONLINE>** Practical molecular, material and process design and process control with artificial intelligence and machine learning	Hiromasa Kaneko	Meiji University
Session 1							
10:40	11:00	Hisato Tanaka Tokyo Electron	Takashi Kurosawa Azbil	**GX-018**	Smart Subfab Transformation using Context-Based Control	Holland Smith	INFICON
11:00	11:20			**PTL-013**	Unified Platform for detecting faults governed by Process Controls	Vishali Ragam	Applied Materials
11:20	11:40			**DA-016**	Mixed-type Defect Pattern Classifications	Takumi Maeda	University of Tsukuba
11:40	12:00			**YM-009**	Defective Wafer Map Classification for Unknown Patterns Using Image Generation Model	Seima Sakaguchi	Mie University
12:00	13:00				Lunch Break & Supplier Exhibition		
Keynote Speech							
13:00	13:45	Hidenori Kakinuma Kioxia		**Keynote**	The Future of Computing - Bits/Neurons/Qubits -	Shintaro Yamamichi	IBM Research -Tokyo, IBM Japan
Session2							
13:45	14:05	Takahiro Tsuchiya United Semiconductor Japan	Tomoya Tanaka Tower Partners Semiconductor	**PTL-007**	Machine Learning Based Virtual Metrology for Effective Process Control in High Product Mix Manufacturing	Hyung Joo Lee	Siemens EDA
14:05	14:25			**PTL-019**	RF sensing method to detect low open area end point	Chuhua Song	INFICON
14:25	14:45			**PTL-008**	Comparison of Numerical Method with Prefixed Profile and Machine Learning-based Method for Wet Etching Amount Prediction	Chihiro Matsui	The University of Tokyo
14:45	15:05			**DA-012**	Population estimation of characteristic variation and its application to circuit simulation for power transistors	Haruka Fukumoto	ROHM Co.,Ltd
15:05	15:25			**DA-017**	Prediction of Defect Rate Using Machine Learning in Assembly Process	Yumiko Miyaji	Sony Semiconductor Manufacturing
15:25	15:45				Supplier Exhibition / Coffee Break		
Tutorial 2 Speech							
15:45	16:30	Kenji Miyake Office Miyake		**Tutorial-2**	Chiplet Integration Technology	Prof. Yoichiro Kurita	Tokyo Institute of Technology
Session3							
16:30	16:50	Hirofumi Tsuchiyama INFICON	Shunichi Shibuki Sony Semiconductor Manufacturing	**DA-011**	Intelligent motor valve with failure prediction feature	Hiroyuki Kawazato	Shinwa Controls Co.,Ltd.
16:50	17:10			**MEP-010**	Development of Versatile Fault Detection Using Image Sensors	Takuya Sugiura	Renesas Electronics
17:10	17:30			**DA-014**	Anomaly detection of semiconductor manufacturing equipment by cluster analysis	Yuki Shiga	KOKUSAI ELECTRIC CORPORATION
17:30	17:50			**PTL-015**	Root Cause Analysis of Plasma Processes Perturbation using Optical Emission Spectroscopy Signals with Modified Autoencoder	Jaehyeon Kim	Sungkyunkwan Univ.
17:50	18:00				Closing		
Conference Room							
18:00	18:30	Koichi Sakamoto Tokyo Electron			Author's Interview		
18:30	19:20				Reception & Supplier Exhibition		
19:20	19:30				Best Paper & Student Award		